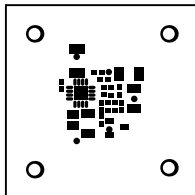
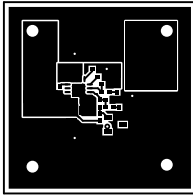


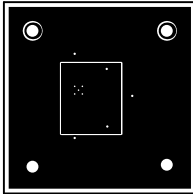
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9166	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 10/22/2013 2:06:16 PM	TEXAS INSTRUMENTS	



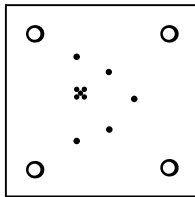
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9166	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 10/22/2013 2:06:16 PM	TEXAS INSTRUMENTS	



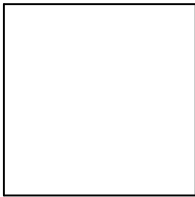
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9166	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/22/2013 2:06:16 PM	TEXAS INSTRUMENTS	



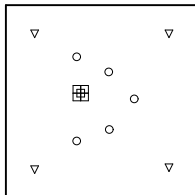
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9166	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/22/2013 2:06:17 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9166	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/22/2013 2:06:17 PM	TEXAS INSTRUMENTS	



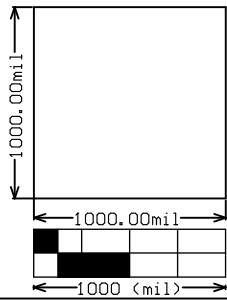
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9166	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/22/2013 2:06:18 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	5	7.874mil (0.2mm)	PTH	Round
○	5	12mil (0.305mm)	PTH	Round
▽	4	63mil (1.6mm)	PTH	Round
	14 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9166	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 10/22/2013 2:06:18 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9166	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 10/22/2013 2:06:19 PM	TEXAS INSTRUMENTS	



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